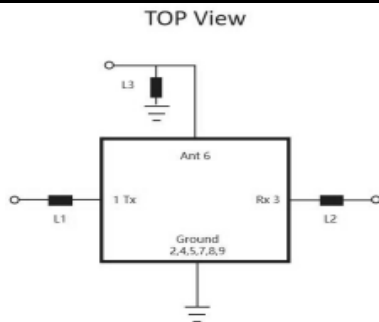


(-40℃ - 95℃)	1574-1606	dB	36	40	-
	1606-1880	dB	36	40	-
	1805-1880	dB	40	44	-
	1920-1980	dB	41	49	-
	2250-2400	dB	40	48	-
	2400-2500	dB	40	48	-
	2500-2700	dB	40	50	-
	2620-2690	dB	45	54	-
	2700-3000	dB	40	47	-
	3000-3800	dB	40	45	-
	3800-4220	dB	28	34	-
	4220-4340	dB	25	31	-
	4340-5000	dB	15	18	-
	5000-6000	dB	10	14	-
Attenuation (1920-1980) (-10℃ - 85℃)	10-1785	dB	30	36	-
	1785-1880	dB	20	27	-
	1990-1900	dB	5	10	-
	2000-2110	dB	3	5	-
	2110-2170	dB	43	49	-
	2255-2400	dB	34	38	-
	2400-2500	dB	30	35	-
	2500-3840	dB	20	25	-
	3840-3960	dB	20	25	-
	3960-5000	dB	20	25	-
	5000-5760	dB	18	24	-
	5760-5940	dB	15	20	-
Attenuation (1920-1980) (-40℃ - 95℃)	10-1785	dB	30	36	-
	1785-1880	dB	20	27	-
	1880-1900	dB	4	10	-
	2000-2110	dB	2.5	5	-
	2110-2170	dB	43	49	-
	2255-2400	dB	34	38	-
	2400-2500	dB	30	35	-
	2500-3840	dB	20	25	-
	3840-3960	dB	20	25	-
	3960-5000	dB	20	25	-
	5000-5760	dB	18	24	-
	5760-5940	dB	15	20	-
Isolation (-10℃ - 85℃)	1920-1980	dB	50	55	-
	2110-2140	dB	50	55	-
	2140-2170	dB	48	52	-
Isolation (-40℃ - 95℃)	1920-1980	dB	50	55	-
	2110-2140	dB	50	55	-
	2140-2170	dB	48	52	-
Operation Temperature	-40℃~+95℃	℃	-	-	-
Storage Temperature	-40℃~+95℃	℃	-	-	-
RF Power Dissipation	+30	dBm	-	-	-
Remark	Note 1: Test Temperature: 25℃±2℃				
	Note 2: Terminating source impedance: 50Ω. Terminating load impedance: 50Ω				
(3)Test Circuit					



Port	Matching Component
Tx	L1 : 1.6 nH (Ideal inductor)
Rx	L2 : 2.0 nH (Ideal inductor)
Ant	L3 : 3.3 nH (Ideal inductor)

Figure 1 Electrical Characteristics: Tx to Ant.

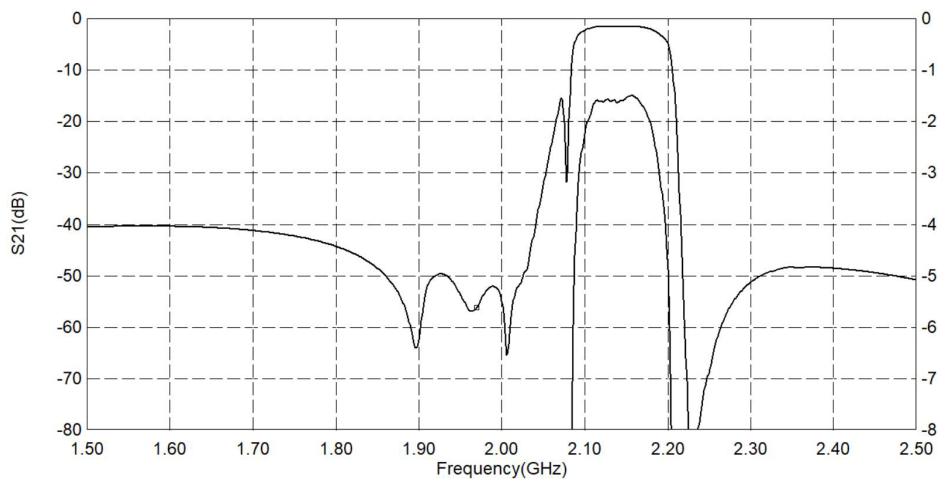


Figure 2 Electrical Characteristics: Tx to Ant.

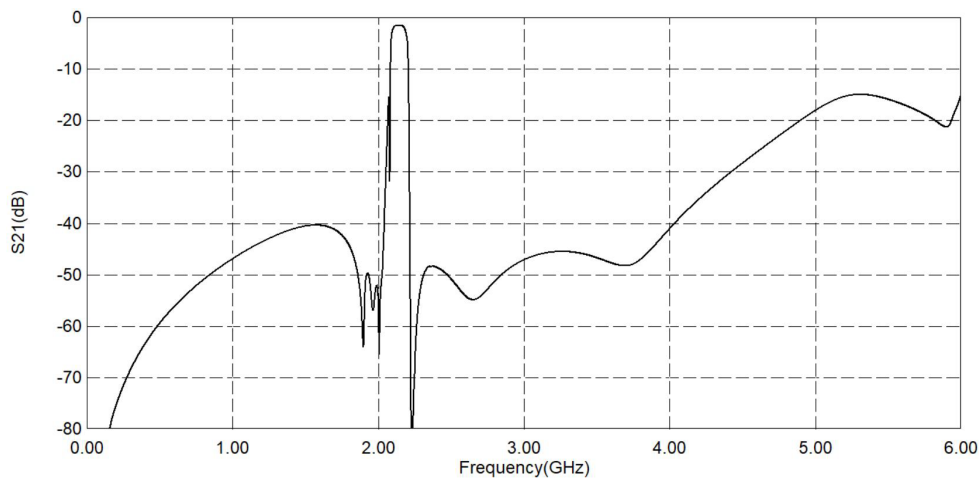


Figure 3 Electrical Characteristics: Ant to Rx.

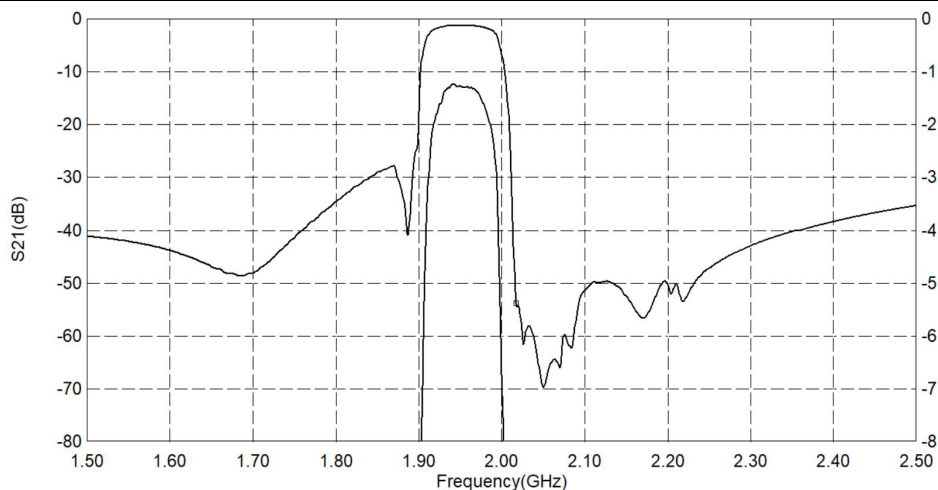


Figure 4 Electrical Characteristics: Ant to Rx.

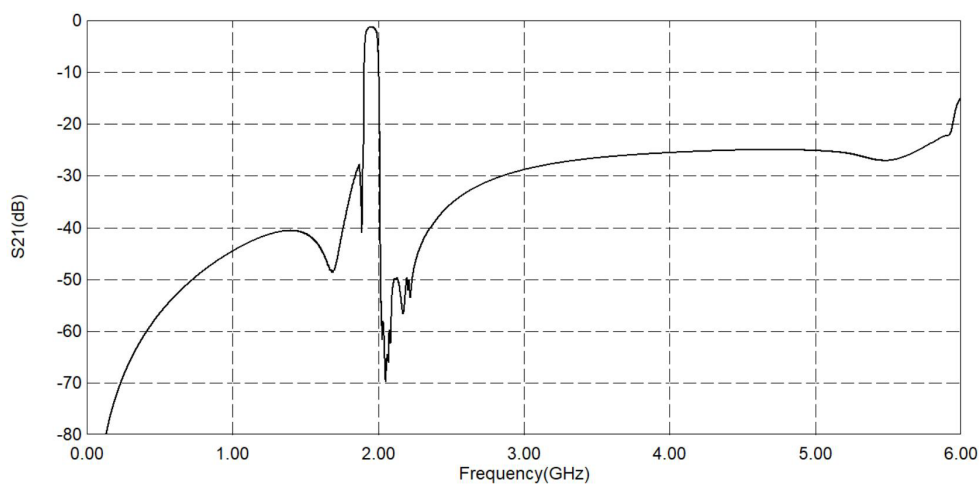


Figure 5 Electrical Characteristics: Tx to Rx.

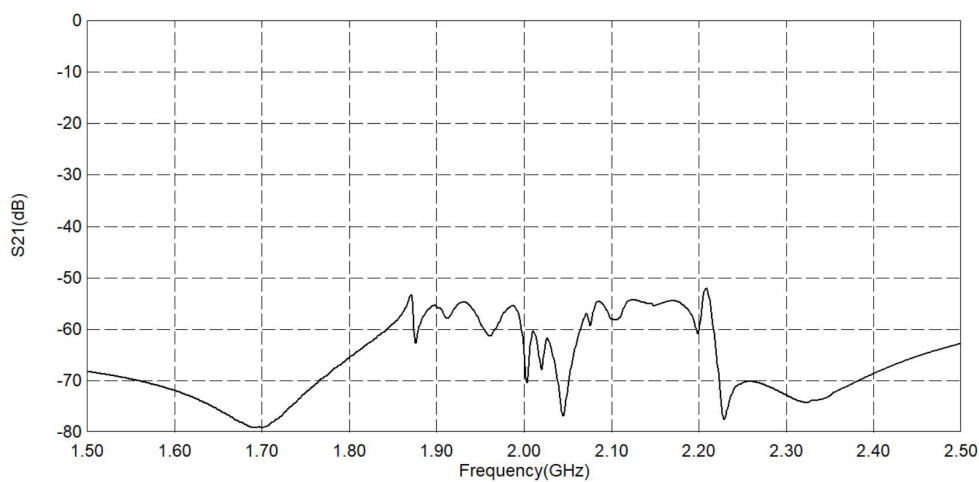


Figure 6 Electrical Characteristics: Tx to Rx.

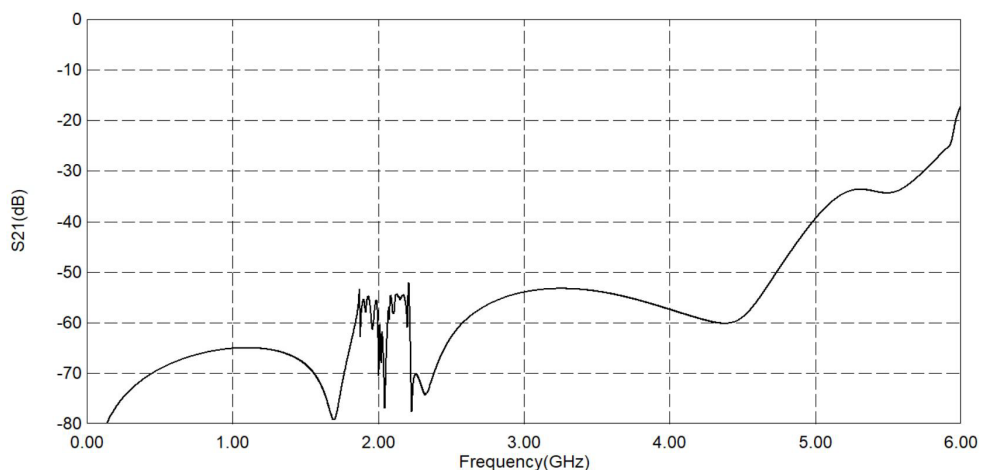
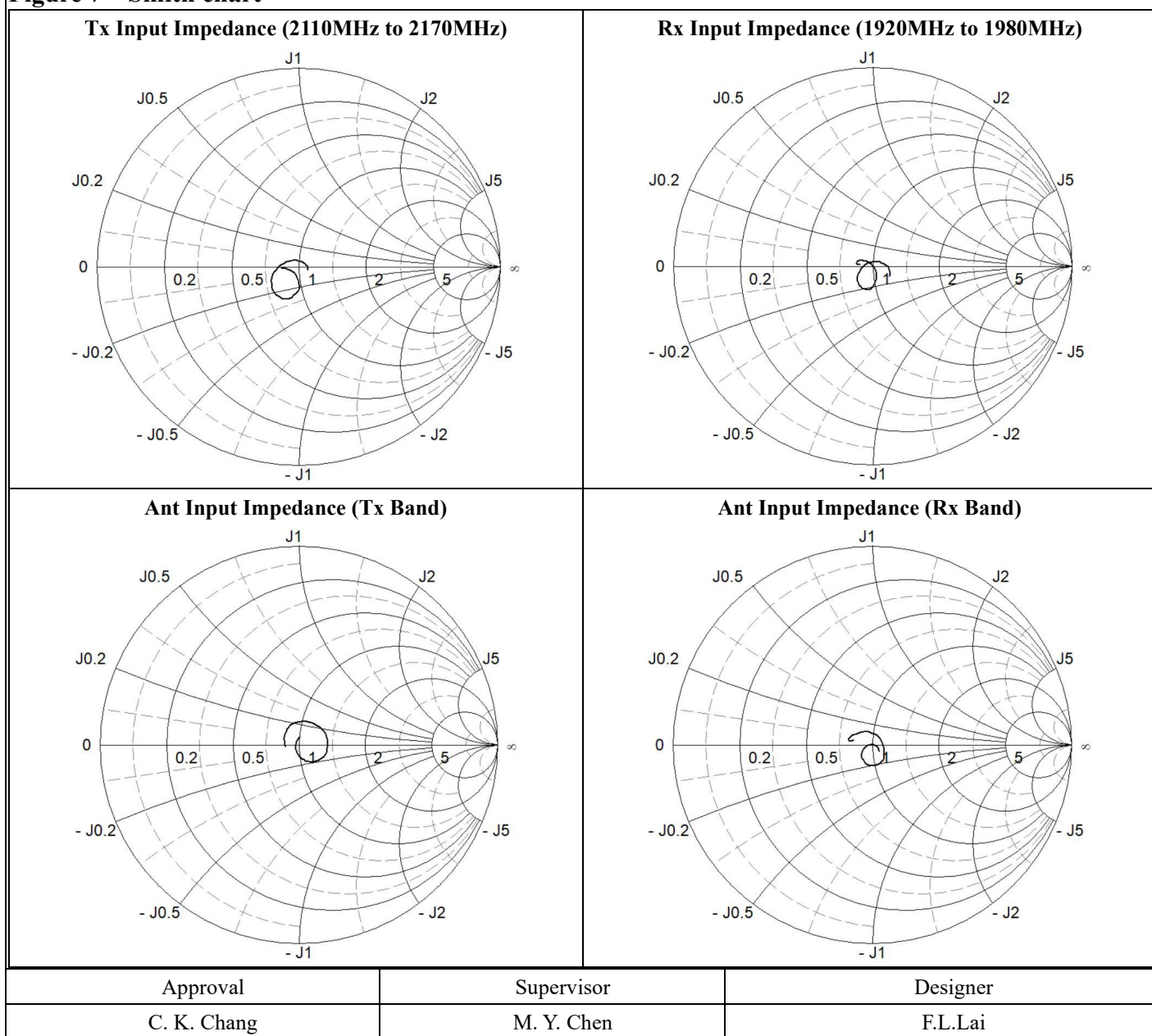
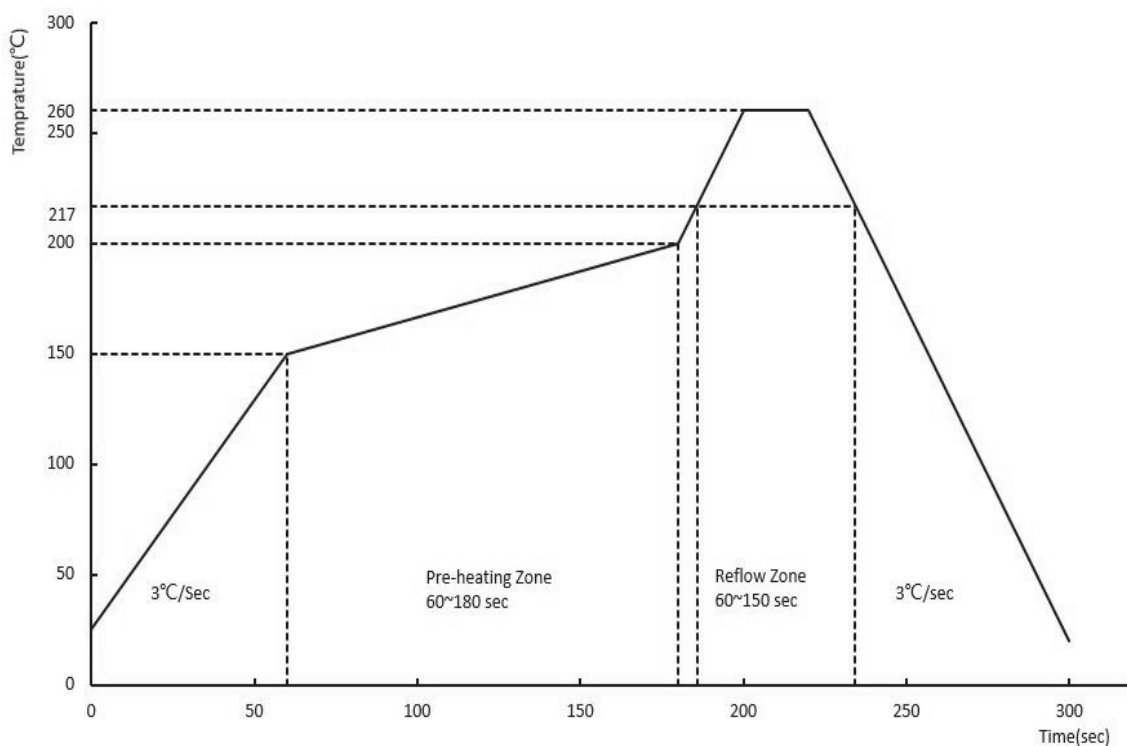


Figure 7 Smith chart



Recommended SMT Solder Profile



Reliability

No.	Test item	Test condition	
1	Temperature Storage	Temperature: 95°C±2°C , Duration: 250h , Recovery time: 2h±0.5h Temperature: -40°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h	
2	Humidity Test	Conditions: 60°C±2°C ,90~95%RH	Duration:250h
3	Thermal Shock	Heat cycle conditions: TA=-40°C±3°C, TB=95°C±2°C, t1=t2=30min, Switch time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.	
4	Vibration Fatigue	Frequency of vibration:10~55Hz Directions: X,Y and Z	Amplitude:1.5mm Duration: 2h
5	Drop Test	Cycle time:10times	Height:1.0m
6	Solder Ability Test	Temperature:245°C±5°C Depth: DIP--2/3, SMD--1/5	Duration:3.0s--5.0s
7	Resistance to Soldering Heat	Thickness of PCB:1mm , Solder condition: 260°C±5°C , Duration:10±1s Temperature of Soldering Iron: 350°C±10°C, Duration: 3~4s, Recovery time : 2 ± 0.5h	